

-	52	method with variable with capacitor) and(stress	USPAT; US-PGPUB; JPO	2004/07/20 12:31
-	2972	method with fabricating with capacitor	USPAT; US-PGPUB; JPO	2004/07/20 12:32
-	15	method with fabricating with capacitor) and(mold adj layer	USPAT; US-PGPUB; JPO	2004/07/20 12:32
-	1870	438/\$.ccls. and(method with fabricating with capacitor)	USPAT; US-PGPUB; JPO	2004/07/20 12:33
-	1677	438/\$.ccls. and(method with fabricating with capacitor)) and(electrode	USPAT; US-PGPUB; JPO	2004/07/20 12:33
-	637	438/\$.ccls. and(method with fabricating with capacitor)) and(upper adj electrode	USPAT; US-PGPUB; JPO	2004/07/20 12:33
-	510	((438/\$.ccls. and(method with fabricating with capacitor)) and(upper adj electrode)) and(lower adj electrode)	USPAT; US-PGPUB; JPO	2004/07/20 12:33
-	192	((438/\$.ccls. and(method with fabricating with capacitor)) and(upper adj electrode)) and(lower adj electrode)) and(opening)	USPAT; US-PGPUB; JPO	2004/07/20 13:36
-	63	unfired with ceramic with plate\$1	USPAT; US-PGPUB; JPO	2004/07/20 13:36
-	37	unfired with ceramic with plate\$1) and(hole\$1	USPAT; US-PGPUB; JPO	2004/07/20 13:44
-	5290	multilayer with board.ti.	USPAT; US-PGPUB; JPO	2004/07/20 13:44
-	1584	multilayer with board.ti.) and(through adj hole\$1	USPAT; US-PGPUB; JPO	2004/07/20 13:45
-	1	(unfired with ceramic with plate\$1) and ((multilayer with board.ti.) and(through adj hole\$1))	USPAT; US-PGPUB; JPO	2004/07/20 13:56
-	40535	laminated with structure	USPAT; US-PGPUB; JPO	2004/07/20 14:01
-	31	laminated with structure.ti. and(through adj hole)	USPAT; US-PGPUB; JPO	2004/07/20 13:57
-	276	laminated with structure) and(ceramic adj plate\$1	USPAT; US-PGPUB; JPO	2004/07/20 14:01
-	89	((laminated with structure) and(ceramic adj plate\$1)) and(through adj hole\$1)	USPAT; US-PGPUB; JPO	2004/07/21 06:49
-	0	enrgy with conditioning.ti.	USPAT; US-PGPUB; JPO	2004/07/21 06:49
-	134	energy with conditioning.ti.	USPAT; US-PGPUB; JPO	2004/07/21 06:55
-	61	6225876/ 5999398/ 5838216/ 5647766/ 5546058/ "5544002"	USPAT; US-PGPUB; JPO	2004/07/21 07:01
-	29	feedthrough with filter.ti.	USPAT; US-PGPUB; JPO	2004/07/21 07:53
-	15	feed near through with filter.ti.	USPAT; US-PGPUB; JPO	2004/07/21 08:57
-	440	361/303 and(semiconductor)	USPAT; US-PGPUB; JPO	2004/07/21 08:57
-	336	361/321.1 and(semiconductor)	USPAT; US-PGPUB; JPO	2004/07/21 09:02

-	38	361/306.3 and(plurality near terminal\$1)	USPAT; US-PGPUB; JPO	2004/07/21 10:20
-	4472	361/\$.ccls. and(electronic adj device)	USPAT; US-PGPUB; JPO	2004/07/21 09:06
-	187	361/\$.ccls. and(electronic adj device)) and(ceramic adj substrate	USPAT; US-PGPUB; JPO	2004/07/21 09:07
-	11	361/306.3 and(plurality near terminal\$1)) and(ratio	USPAT; US-PGPUB; JPO	2004/07/21 10:14
-	64	multilayer with capacitor.ti. and(via adj hole\$1 or hole\$1)	USPAT; US-PGPUB; JPO	2004/07/21 10:17
-	6	multilayer with capacitor.ti. and(via adj hole\$1 or hole\$1)) and(ratio	USPAT; US-PGPUB; JPO	2004/07/21 10:15
-	0	multilayer with capacitor.ti. and(axial adj length)	USPAT; US-PGPUB; JPO	2004/07/21 10:17
-	1430	lamine\$3 with structure.ti.	USPAT; US-PGPUB; JPO	2004/07/21 10:22
-	197	lamine\$3 with structure.ti.) and(via adj hole\$1 or hole\$1	USPAT; US-PGPUB; JPO	2004/07/21 10:20
-	29	((lamine\$3 with structure.ti.) and(via adj hole\$1 or hole\$1)) and(ratio)	USPAT; US-PGPUB; JPO	2004/07/21 10:21
-	1235	lamine\$3 with capacitor.ti.	USPAT; US-PGPUB; JPO	2004/07/21 10:22
-	78	lamine\$3 with capacitor.ti.) and(via near hole\$1 or hole\$1	USPAT; US-PGPUB; JPO	2004/07/21 13:42
-	0	laminated with structure.ti. and(ratio with cylinder)	USPAT; US-PGPUB; JPO	2004/07/21 13:46
-	0	laminated with capacitor.ti. and(ratio with cylinder)	USPAT; US-PGPUB; JPO	2004/07/21 13:44
-	131	laminated with structure.ti. and(ratio)	USPAT; US-PGPUB; JPO	2004/07/21 13:44
-	11	laminated with structure.ti. and(ratio)) and(hole\$1	USPAT; US-PGPUB; JPO	2004/07/21 13:44
-	6	laminated with structure.ti. and(axial adj length)	USPAT; US-PGPUB; JPO	2004/07/21 13:47
-	0	laminated with capacitor.ti. and(axial adj length)	USPAT; US-PGPUB; JPO	2004/07/21 13:48
-	3	laminated with capacitor.ti. and(plurality near hole\$1)	USPAT; US-PGPUB; JPO	2004/07/22 13:35
-	0	ceramic with young adj module with tensile adj strength	USPAT; US-PGPUB; JPO	2004/07/22 13:36
-	0	ceramic with module with tensile adj strength	USPAT; US-PGPUB; JPO	2004/07/22 13:36
-	1085	ceramic with tensile adj strength	USPAT; US-PGPUB; JPO	2004/07/22 13:37
-	0	ceramic with tensile adj strength) and(young adj module	USPAT; US-PGPUB; JPO	2004/07/22 13:37
-	44	ceramic with tensile adj strength) and(module\$1	USPAT; US-PGPUB; JPO	2004/07/22 13:40